



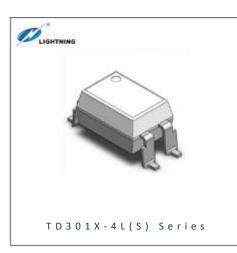
PRODUCT DATASHEET



- DC Input Photo Coupler
 SMD4
- Random-Phase TRIAC

TD301X-4L(S)(T1)-GV





APPLICATIONS:

- Solenoid/valve controls
- Lighting controls
- Motor controls
- Temperature controls
- Static AC power switches
- Solid state relays

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 Interfacing microprocessors to 115 to 240VAC peripherals

TD301X-4L(S) Series

DESCRIPTION:



The TD301X-4L(S) series combine an AlGaAs infrared emitting diode as the emitter which is optically coupled to a monolithic silicon random-phase photo TRIAC in a plastic DIP4 package with SMD4 lead forming option.

With the robust coplanar double mold structure, TD301X-4L(S) series provide the most stable isolation feature.

FEATURES:

- High isolation 5000Vrms
- DC input with random-phase photo TRIAC output
- Operating temperature range -40°C to +100°C
- REACH & RoHS compliance; Halogen free
- MSL class 1
- Regulatory Approvals:
 - o UL UL1577
 - o VDE EN60747-5-5 (VDE0884-5)
 - o CQC GB4943.1, GB8898
 - cUL CSA Component Acceptance Service Notice 5A
- Packing: T1/T2: 1500pcs/reel; T3/T4: 1000pcs/reel

CAL AL COO Partner with:



NAMING & ORDERING INFORMATION:

Naming Information:

TD301 X - 4L (S) (T1) - G V				
TD301X-4L	Part Number			
×	Selection: LED Trigger Current (X=0~2)			
4L	DIP 4 Package			
S	Lead Form Option: SMD4			
T1	Selection: Tape and Reel Option (T1(default)/T2/T3/T4)			
G	Green Option			
V	VDE Option			

Ordering Information:

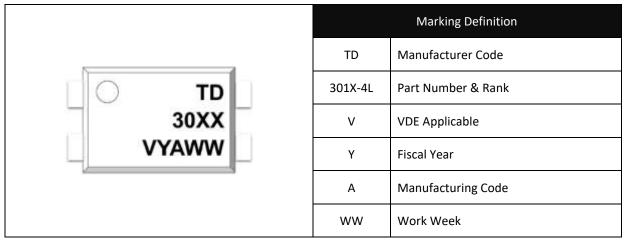
TD301 <u>X</u> -4L(S)(T1)-GV							
\underline{X} = Selection: LED Trigger Current (X=0~2)							
Part Number	Values			Unit	Test Condition		
	Symbol	Symbol	Min. Typ.	Тур.	Max.	Onit	Test condition
TD3010-4L(S)(T1)-GV				15		L =100m A	
TD3011-4L(S)(T1)-GV	I _{FT}			10	mA	I™=100mA Terminal	
TD3012-4L(S)(T1)-GV				5		Voltage=3V	

Version No.	Original Release Date
Rev: A00	05/09/2024



Schematic Diagram: PIN Definition 1 Anode 2 Cathode 3 Terminal 4 Terminal

Marking Information:



Labelling Information:





Absolute Maximum Ratings:

Parameter	Symbol	Ratings	Unit			
INPUT						
Forward Current	IF	60	mA			
Reverse Voltage	VR	6	V			
Junction Temperature	Tj	125	°C			
Input Power Dissipation	Pı	100	mW			
OUTPUT						
Off-State Output Terminal Voltage	V _{DRM}	250	V			
Peak Repetitive Surge Current PW=100μs, 120pps	Ітѕм	1	А			
On-State RMS Current	It(rms)	100	mA			
Junction Temperature	Tj	125	°C			
Output Power Dissipation	Po	300	mW			
COMMON						
Total Power Dissipation	P _{tot}	400	mW			
Isolation Voltage	Viso	5000 ^{*1}	Vrms			
Operating Temperature	Topr	-40~+100	°C			
Storage Temperature	T _{stg}	-55~+125	°C			
Soldering Temperature	T _{sol}	260 *2	°C			

*1. AC for 1 minute, R.H.=40~60%.

*2. For 10 seconds max.



ELECTRICAL CHARACTERISTICS:

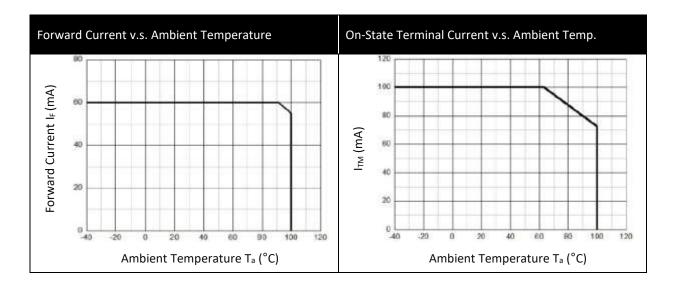
Electrical Optical	Characteristics at T _a =25°C:
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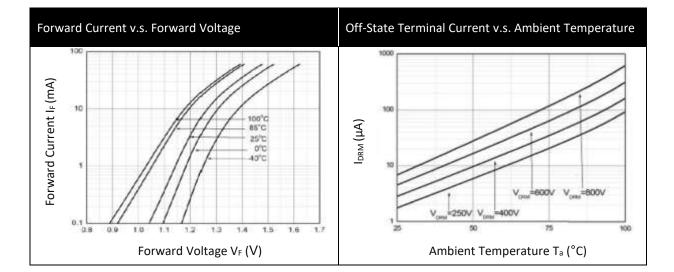
Paramete	er	Symbol	Min.	Values Typ.	Max.	Unit	Test Condition
INPUT							
Forward Voltage		V _F		1.24	1.4	V	I⊧=10mA
Reverse Current		I _R			10	μA	V _R =6V
Input Capacitance		Cin		8.5	250	pF	V=0, f=1kHz
			OUTPL	JT			
Peak Off-State Curre Either Direction	nt	Idrm			100 *1	nA	V_{DRM} =Rated V_{DRM} I _F =0
Peak On-State Voltag Either Direction	ge	V _{TM}		1.58	2.5	v	I _{TM} =100mA
Critical Rate of Rise of Voltage	of Off-State	dV/dt	1000			V/µs	V _{PEAK} =400V I _F =0
	TRANSFER CHARACTERISTICS						
	TD3010-4L				15		100m
LED Trigger Current	TD3011-4L	I _{FT}			10	mA	I™=100mA Terminal Voltage=3V
	TD3012-4L				5		
Holding Current		Ін		257		μΑ	
Isolation Resistance		R _{ISO}	10^12	10^14		Ω	DC=500V, 40~60% R.H.
Floating Capacitance		Сю		0.4	1	pF	V=0, f=1MHz

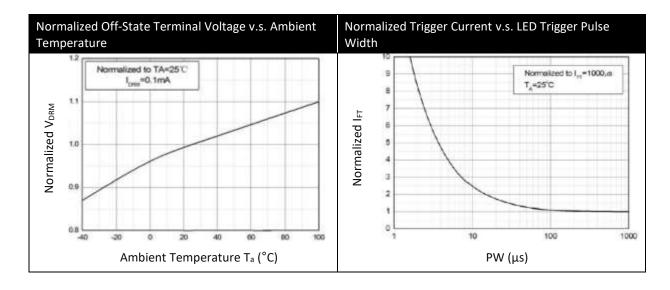
*1. Test voltage must be applied within dV/dt rating.



CHARACTERISTIC CURVES:

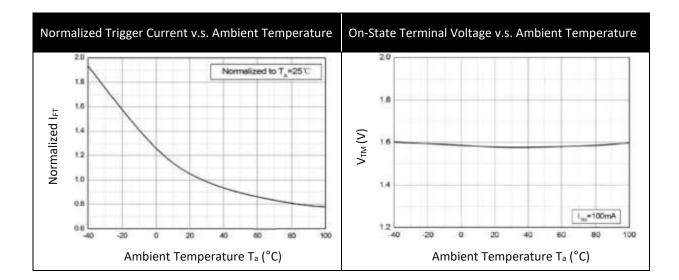


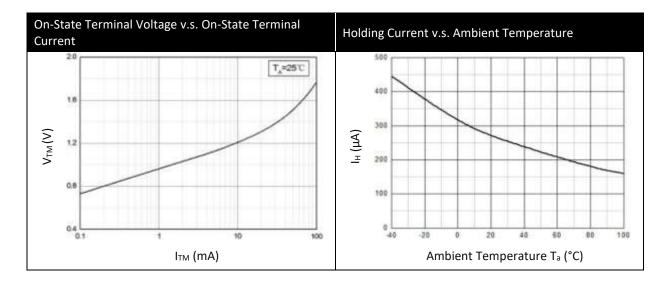


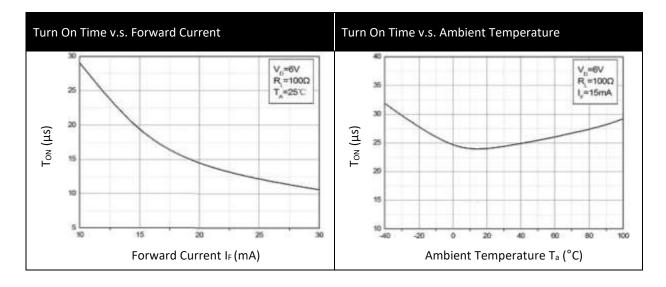




CHARACTERISTIC CURVES:

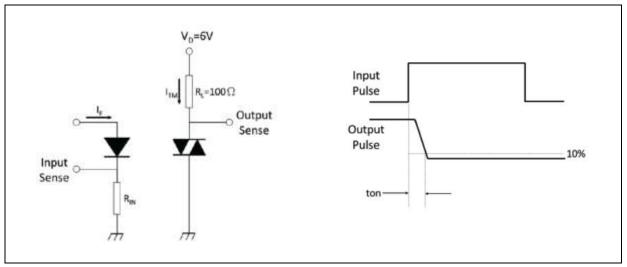






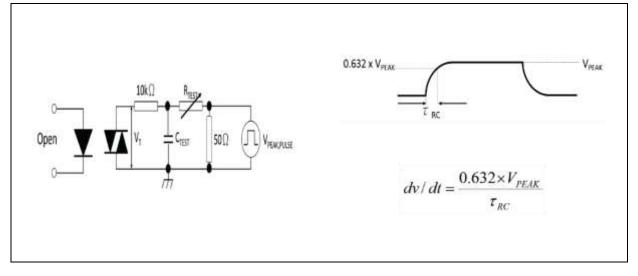


TEST CIRCUIT:



Test Circuit and Waveforms of Turn On Time:

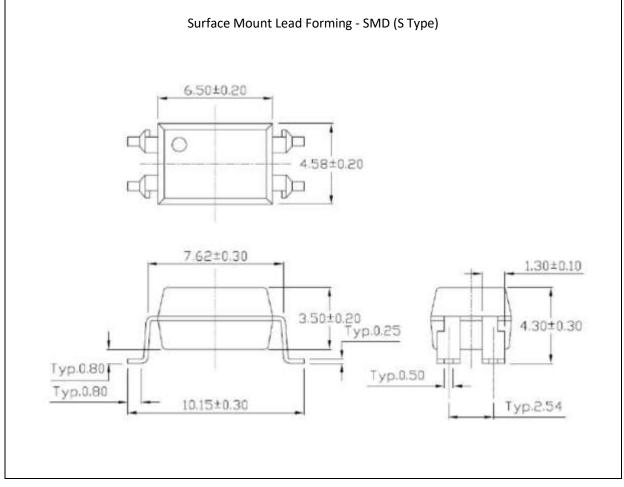
Test Circuit and Waveforms of dV/dt:





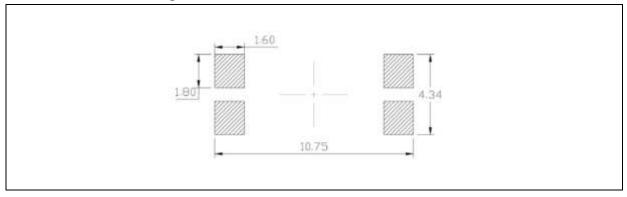
OUTLINE DIMENSION:

Package Dimension:



1. All dimensions are in millimetre (mm).

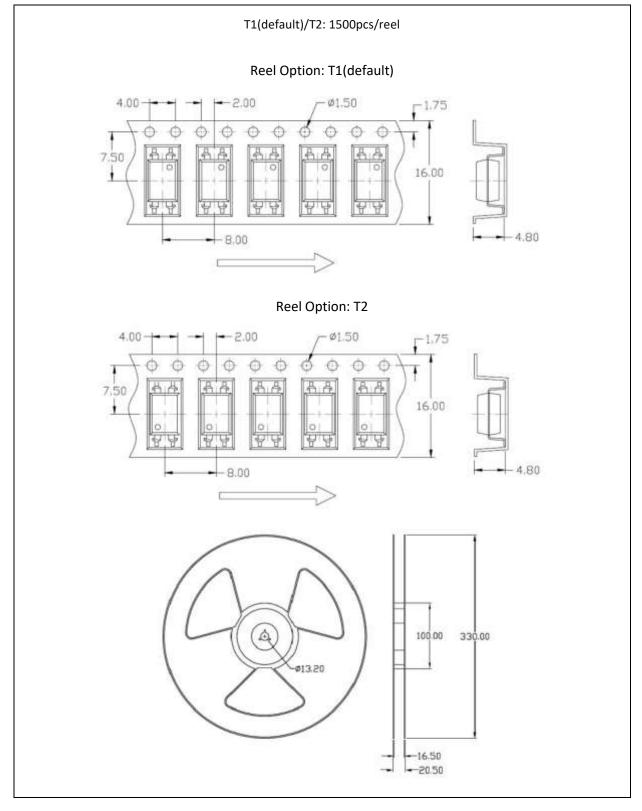
Recommended Soldering Mask:



1. Dimensions are in millimetre (mm).

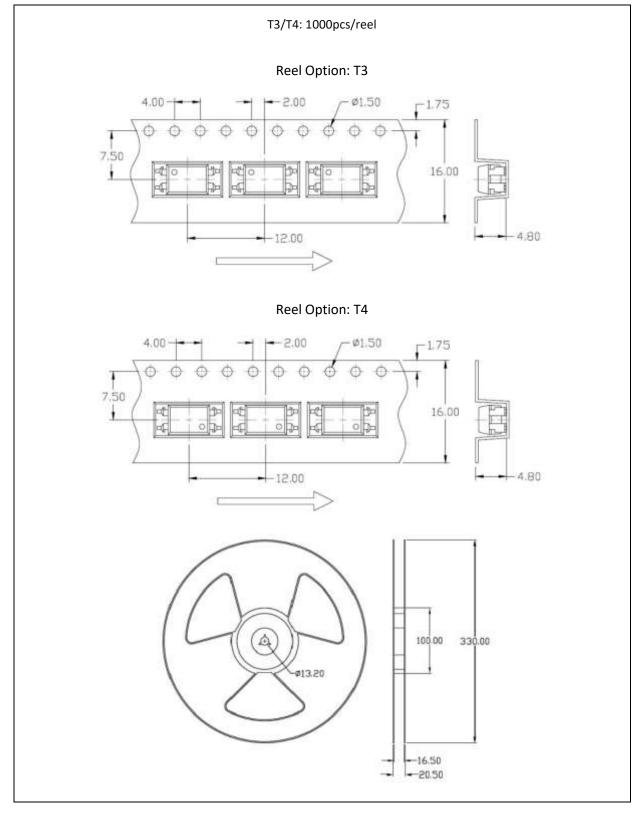


Reel Dimension:





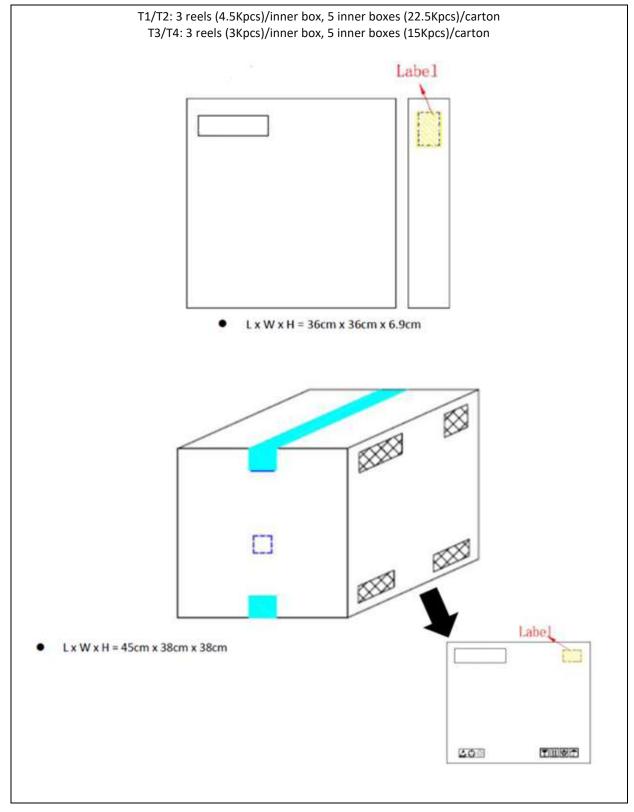
Reel Dimension:





PACKING SPECIFICATION:

Box Dimension:





RECOMMENDED SOLDERING PROFILE:

Reflow Information:

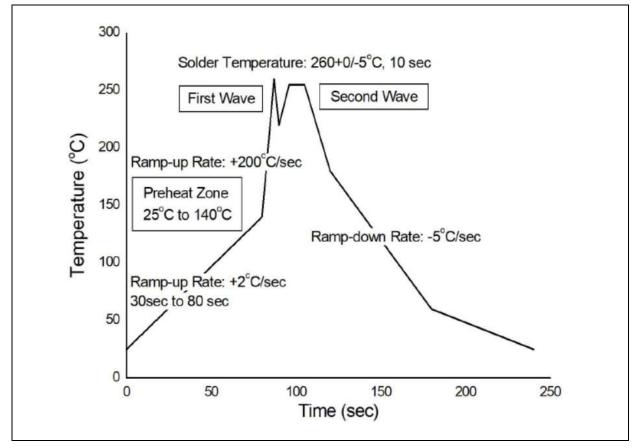
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Supplier T _p ≥	T _c T _c T _c -5°C	er $T_p \leq T_c$ User t_p
		t _p → t _p →
		PC-020
Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Profile Feature Temperature Min. (T _{smin})	Sn-Pb Assembly Profile 100°C	Pb-Free Assembly Profile 150°C
Temperature Min. (T _{smin})	100°C	150°C
Temperature Min. (T _{smin}) Temperature Max. (T _{smax})	100°C 150°C	150°C 200°C
Temperature Min. (T _{smin}) Temperature Max. (T _{smax}) Time (t _s) from (T _{smin} to T _{smax})	100°C 150°C 60-120 seconds	150°C 200°C 60-120 seconds
Temperature Min. (T _{smin}) Temperature Max. (T _{smax}) Time (t _s) from (T _{smin} to T _{smax}) Ramp-up Rate (t _L to t _P)	100°C 150°C 60-120 seconds 3°C/second max.	150°C 200°C 60-120 seconds 3°C/second max.
Temperature Min. (T _{smin}) Temperature Max. (T _{smax}) Time (t _s) from (T _{smin} to T _{smax}) Ramp-up Rate (t _L to t _P) Liquidous Temperature (T _L)	100°C 150°C 60-120 seconds 3°C/second max. 183°C	150°C 200°C 60-120 seconds 3°C/second max. 217°C
Temperature Min. (T _{smin}) Temperature Max. (T _{smax}) Time (t _s) from (T _{smin} to T _{smax}) Ramp-up Rate (t _L to t _P) Liquidous Temperature (T _L) Time (t _L) Maintained Above (T _L)	100°C 150°C 60-120 seconds 3°C/second max. 183°C 60-150 seconds	150°C 200°C 60-120 seconds 3°C/second max. 217°C 60-150 seconds
Temperature Min. (Tsmin)Temperature Max. (Tsmax)Time (ts) from (Tsmin to Tsmax)Ramp-up Rate (tL to tP)Liquidous Temperature (TL)Time (tL) Maintained Above (TL)Peak Body Package Temperature	100°C 150°C 60-120 seconds 3°C/second max. 183°C 60-150 seconds 235°C +0°C / -5°C	150°C 200°C 60-120 seconds 3°C/second max. 217°C 60-150 seconds 260°C +0°C / -5°C



RECOMMENDED SOLDERING PROFILE:

Wave Soldering (JESD22-A111 Compliant):



Hand Soldering:

Soldering Temperature	380±5°C
Soldering Time	3 sec max.

Note:

- One time soldering is recommended for all soldering methods.
- Do not solder more than three times for IR reflow soldering.